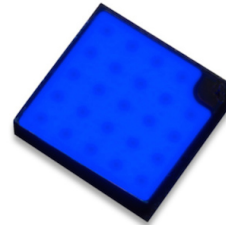


# C4L-D40X2

Deep Blue LED die 40 mil



This die specification contains the basic features of the 2nd generation ThinGaN UX3 dice from OSRAM Opto Semiconductors. Remarkable light extraction is reached by a particular top emitting design with vertical chip structure. Furthermore the LED die shows excellent reliability behaviour and optimized current spreading



## Features

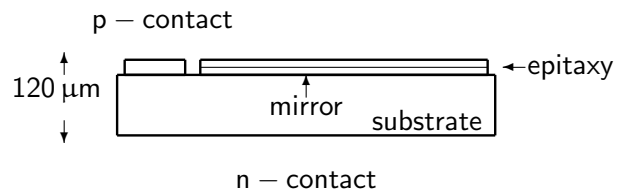
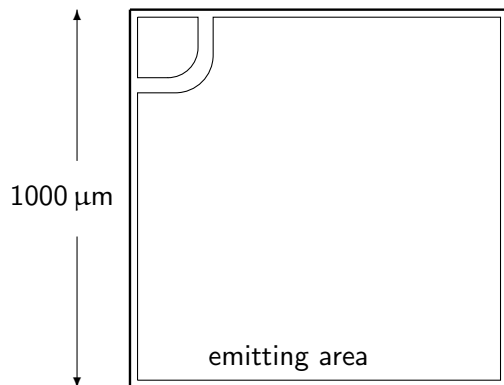
- Highest brightness InGaN chip
- Polarity p-side up
- Chip with optimized current distribution
- Grouping: radiant power, wavelength
- Top emitting device

## Applications

- Solid state lighting
- LCD backlighting
- Lamps
- Displays
- Light indicators

Ordering information: C4L-D40X2-3335-X (435 ... 455 nm, 400 ... 800 mW)

## Delineation



## Mechanical characteristics

DESCRIPTION	MINIMUM	TYPICAL <sup>1</sup>	MAXIMUM
Chip size (µm)	950	1000	1050
Chip height (µm)	100	120	140
Bond pad diameter (µm)	130	150	170
Top contact	Anode (p), gold		
Bottom contact	Cathode (n), gold alloy		
Die attach	Epoxy bonding, Soldering		

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## Electro-optical characteristics ( $T_A = 25^\circ\text{C}$ )<sup>2</sup>

PARAMETER	SYMBOL	CONDITION	MIN.	TYP. <sup>1</sup>	MAX.	UNIT
Forward voltage	$V_F$	$I_F = 350\text{ mA}$	2.70		3.30	V
Dominant wavelength	$\lambda_{dom}$	$I_F = 350\text{ mA}$	435		455	nm
Radiant power	$\Phi_e$	$I_F = 350\text{ mA}$	400	600	800	mW

## Maximum ratings ( $T_A = 25^\circ\text{C}$ )<sup>3</sup>

PARAMETER	SYMBOL	VALUE	UNIT
Operating temperature range	$T_{op}$	-40 ... 125	$^\circ\text{C}$
LED junction temperature	$T_j$	150	$^\circ\text{C}$
Forward minimum current	$I_F$	30	mA
Forward maximum current	$I_F$	1000	mA
Forward peak current ( $t < 10\mu\text{s}; D = 0.005; T_S = 25^\circ\text{C}$ )	$I_{FM}$	2500	mA

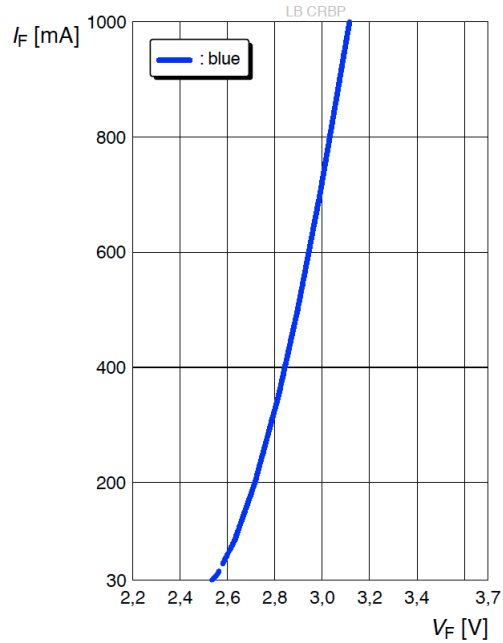
## Binning ( $I_F = 350\text{ mA}$ )<sup>4</sup>

		WAVELENGTH (NM)						
		435-440	437.5-442.5	440-445	442.5-447.5	445-450	447.5-452.5	450-455
Radiant power (mW)	> 400	W33	WM33	X33	XM33	Y33	YM33	Z33
	> 500	W34	WM34	X34	XM34	Y34	YM34	Z34
	> 640	W35	WM35	X35	XM35	Y35	YM35	Z35

Actual binning is 2.5 nm, but single 2.5 nm wavelength bins cannot be ordered. There are intermediate brightness levels available. Please contact us for more information

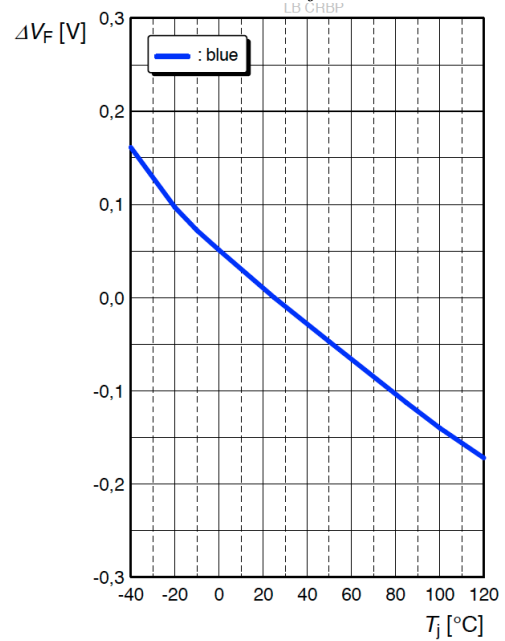
## Forward Current

$$I_F = f(V_F); T_S = 25^\circ C$$



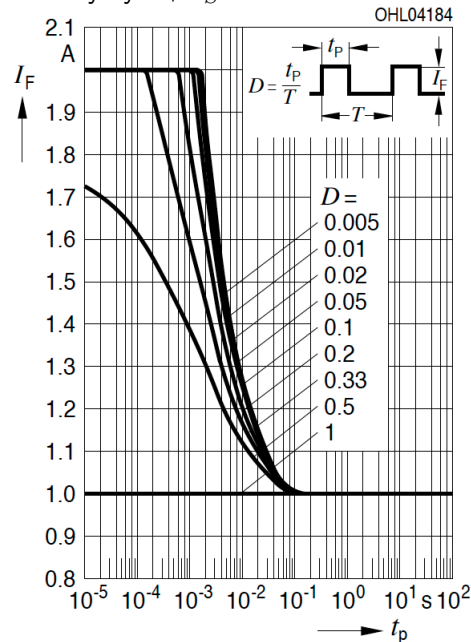
## Relative forward voltage

$$\Delta V_F - V_F(25^\circ C) = f(T_j); I_F = 350 mA$$



## Permissible Pulse Handling Capability

D: Duty cycle;  $T_S = 25^\circ C$



The values shown in the diagrams above, represent the chip in a OSLOM package.

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Deep Blue LED die 40 mil



## Handling and Storage Conditions

Storage time for wafers in sealed condition shall not exceed 6 months (storage ambient conditions:  $T_a = 15 \dots 30^\circ C$ ; relative humidity:  $< 60\%$ ). The hermetically sealed shipment lot shall be opened under temperature and moisture controlled cleanroom environment only. Customers have to follow the according rules for desposition as the material can be hazardous for humans and the environment. Chips are placed on a blue foil, which may contain the following substance in a concentration of circ.18% wt: Bis (2-ethyl(hexyl)phthalate) (DEHP) [CAS #: 117-81-7; EC # 204-211-0]. Dice have to be handled ESD sensitive.

## Packing

Chips are placed on a blue foil inside a 6 inch ring or alternatively on a blue foil (mylar). For shipment the wafers of a shipment lot are arranged to stacks. The stack is put in a plastic ESD bag with maximum of 14 wafers in one bag. Maximum of 4 bags is put in a packaging box. Maximum of 5 packaging boxes is put in a shipping carton which is sealed for storage and shipment. Please use the recycling operators familiar to you. If required you can ask for our help. Please get in touch with your nearest sales office. By agreement we will take packing material back, if sorted. Transport costs of any kind must be paid by customers. For packing material that is returned to us unsorted or which we are not obliged to accept, any costs incurred will be invoiced to you.

## Design Objectives

The chip design was developed and released based on the producer's standard assembly procedures and packaging. Bond strength properties are in accordance to MIL-STD-750D, method 2037. Whether the chip fits to the customer's products with its according die and wire bond procedures and packaging must be evaluated by the customer himself. If workability problems arise after this release a mutually conducted problem solving procedure has to be set up, if the chips are suspected of contributing to the problems. The chips are produced with best effort, but on chip level a subset of the chip characteristics can be determined only. Performance of the chip in the customer's products can only be determined by the customer himself.

## Returns and Complaints

For complaints and returns of material a RMA-number is necessary. Samples for analysis purposes can be send to us without credit.

## Shipping Conditions

If not otherwise arranged, the "General Terms of Business of Chips 4 Light GmbH" apply for any shipment. If this document is not familiar to you, please request it at our nearest sales office.

## Disclaimer Attention please!

- **Components used in life-support devices or systems must be expressly authorized for such purpose!**  
Critical components<sup>5</sup> may only be used in life-support devices<sup>6</sup> or systems with the express written approval by us.
- All products, product specifications and data to improve reliability, function, design or otherwise are subject to change without notice .
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- The information describes the type of component and shall not be considered as assured characteristics. Due to technical requirements components may contain dangerous substances. For information on the types in question please contact our Sales Organization.
- Lead free product - RoHS compliant.

- The quality level of the final visual inspection shall comply to an AQL of 1.0 (according to MIL-STD-105E, level II), if the customer performs an incoming visual inspection of a shipment.
- All chips are checked according to the producer's specification of the visual inspection. If this document is not familiar to you, please request it at our nearest sales office.

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<sup>1</sup>Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

<sup>2</sup>Measurements are done with an accuracy of  $\pm 15\%$ . Correlation to customer's equipment and products is required.

<sup>3</sup>Maximum ratings are package dependent and may differ between packages. The forward current is not limited by the die but by the effect of the LED junction temperature on the package. If you need more information on pulsed operation, please contact your next sales office about possible driving conditions. If not otherwise specified the maximum pulse current may not exceed the maximum current in continuous mode.

<sup>4</sup>There may be more than one bin on one single foil. Single bins cannot be ordered.

<sup>5</sup>A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or the effectiveness of that device or system.

<sup>6</sup>Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health and the life of the user may be endangered.